



Material declaration form

General information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information	*: Required Field	
Supplier information			
Company name*	STMicroelectronics	Response date*	2025-04-24
Authorized representative*	Floriana SAN BIAGIO	Representative title	APMS Material Declaration Champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement			
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Legal statement			
Supplier acceptance *	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Manufacturing item number	Manufacturing item name	Version	Manufacturing site	Date
	77AA*MY2TCCB	B	CA2A	2025-04-24
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	6.0	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy		Comment
Not Applicable	Nickel/Gold (Ni/Au), electrolytic	Copper Alloy		0
Comment	VFLGA2.5X3X.86 14L P.5 L.475X.25; MDF is valid for IIS2DULPXTR, LIS2DUX12TR, LIS2DUXS12TR			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
7c-I	7c-I-Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound	

QueryList : ELV directive : 2000/53/EC amended 2020/363_ March 2020		Response
1 - Product(s) meets EU ELV requirement without any exemptions		false
2 - Product(s) meets EU ELV requirements by application of the selected exemption(s)		true
Exemption Id.	Description	
10(a)	10(a) - Electrical and electronic components which contain lead in a glass or ceramic, in a glass or ceramic matrix compound, in a glass-ceramic material, or in a glass-ceramic matrix compound.	

QueryList : California Prop65 list, dated 3rd January 2025			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			true
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.063	Die	10500
Lead	0.088	lead in glass	14667
Lead-Borate Glass	0.146	passivation	24333
Bisphenol A	0.001	base	167

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014					Response
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products					false
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products					false
Hazardous substance					
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE	
X	O	O	O	O	
Dies					
is Homogeneous Material containing Lead					

QueryList : REACH- REACH-21st January 2025				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Homogeneous Material above the limits per the definition within REACH				true



CategoryLevel_Name	CategoryLevel_Threshold	Amount in homogeneous material (mg)	Application - homogeneous material	ppm in homogeneous material
diphenyl(2,4,6-trimethylbenzoyl)phosphine oxide	1000 ppm	0.004	Substrate	2825

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false



QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Cobalt, Gold, Tantalum,
This product is in the scope of the responsible metals sourcing, its compliance is covered by our company processes .	

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	false

QueryList:Stockholm Convention Persistent Organic Pollutants	Response
Product is compliant with Stockholm Convention Persistent Organic Pollutants Annex I	true

QueryList:EUSRR Directive	Response
Product contains hazardous materials listed in EUSRR Annex II	True

PFAS/PTFE Declaration	Response
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene,Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	False

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True



Material composition declaration : note : Substance present with less 0.001mg will not be declared in this document						Manufacturing item name	77AA*MY2TCB		6.0000		5999999.0	1000001.0		
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)		
Dies	M-011 Other inorganic materials	2.469	mg	supplier	die	Silicon(Si)	7440-21-3		2.232	mg	904010	372000		
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.006	mg	2430	1000		
				supplier	metallisation	Copper(Cu)	7440-50-8		0.022	mg	8910	3667		
				supplier	metallisation	Cobalt(Co)	7440-48-4		0.006	mg	2430	1000		
				supplier	metallisation	Tantalum(Ta)	7440-25-7		0.004	mg	1620	667		
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.002	mg	810	333		
				supplier	metallisation	Zirconium(Zr)	7440-67-7		0.001	mg	405	167		
				supplier	Passivation	Silicon Nitride (SiN)	12033-89-5		0.007	mg	2835	1167		
				supplier	passivation	Silicon Oxide	7631-86-9		0.043	mg	17416	7167		
					JIG-R & California 65	glass	Lead-Borate Glass	65997-18-4	7c-I-Electrical and electron	0.146	mg	59133	24333	
Substrate	M-015 Other organic materials	1.416	mg	supplier	laminate	Fiber glass	65997-17-3		0.209	mg	147599	34833		
				supplier	laminate	Bisphenol F type epoxy resin	9003-36-5		0.117	mg	82627	19500		
				supplier	laminate	Bismaleimide (B)	105391-33-1		0.071	mg	50141	11833		
				supplier	laminate	Triazine (T)	25722-66-1		0.070	mg	49435	11667		
				supplier	laminate	Aluminium hydroxide	21645-51-2		0.005	mg	3531	833		
				supplier	laminate	Zinc hydroxide	20427-58-1		0.001	mg	706	167		
				supplier	laminate	Calcium sulfate	7778-18-9		0.002	mg	1412	333		
				SVHC	laminate	BPA	80-05-7		0.001	mg	706	167		
				supplier	laminate	Acrylic resin	9003-01-4		0.097	mg	68503	16167		
				supplier	laminate	Barium sulfate	7727-43-7		0.041	mg	28955	6833		
				supplier	laminate	epoxy resin	85954-11-6		0.036	mg	25424	6000		
				supplier	laminate	Talc	14807-96-6		0.025	mg	17655	4167		
				supplier	laminate	Aromatic hydrocarbon	64742-94-5		0.011	mg	7768	1833		
				supplier	laminate	Methoxymethylethoxy propanol	34590-94-8		0.027	mg	19068	4500		
				supplier	laminate	Acetate compound	112-15-2		0.027	mg	19068	4500		
				supplier	laminate	DPMA	88917-22-0		0.005	mg	3531	833		
				SVHC	laminate	Diphenyl-trimethylbenzoyl phosphine oxide	75980-60-8		0.004	mg	2825	667		
					M-004 Copper and its alloys	supplier	laminate	Copper(Cu)	7440-50-8		0.591	mg	417373	98500
					M-006 Nickel and its alloys	California 65	laminate	Nickel(Ni)	7440-02-0		0.063	mg	44492	10500
						supplier	laminate	Gold(Au)	7440-57-5		0.013	mg	9181	2167
Die attach-1	M-015 Other organic materials	0.082	mg	supplier	tape	Lintec-Tape-Polyolefin resin-IP	proprietary		0.048	mg	585366	8000		
				supplier	tape	LINTEC-TAPE-Epoxy acrylic resin-IP	Proprietary		0.005	mg	60976	833		
				supplier	tape	epoxy resin	29690-82-2		0.006	mg	73171	1000		
				supplier	tape	Polyethylene terephthalate	25038-59-9		0.023	mg	280488	3833		
Die attach-2	M-015 Other organic materials	0.095	mg	supplier	glue	Amorphous silica	7631-86-9		0.039	mg	410526	6500		
				supplier	glue	Polyethylen terephthalate	25038-59-9		0.024	mg	252632	4000		
				supplier	glue	Acrylic resin	9003-01-4		0.016	mg	168421	2667		
				supplier	glue	Epoxyde bisphenol A resin	25068-38-6		0.016	mg	168421	2667		
Bonding wire	M-008 Precious metals	0.123	mg	supplier	wire	Gold(Au)	7440-57-5		0.122	mg	991870	20333		
				supplier	wire	Palladium(Pd)	7440-05-3		0.001	mg	8130	167		
Encapsulation	M-015 Other organic materials	1.815	mg	supplier	mold compound	Silica vitreous	60676-86-0		1.643	mg	905234	273833		
				supplier	mold compound	Epoxyde bisphenol A resin	25068-38-6		0.045	mg	24793	7500		
				supplier	mold compound	Epoxy resin	proprietary		0.073	mg	40220	12167		
				supplier	mold compound	Phenol Resin	proprietary		0.045	mg	24793	7500		
				supplier	mold compound	Carbon black	1333-86-4		0.009	mg	4959	1500		
									mg					